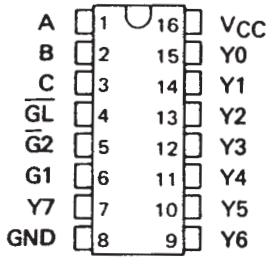
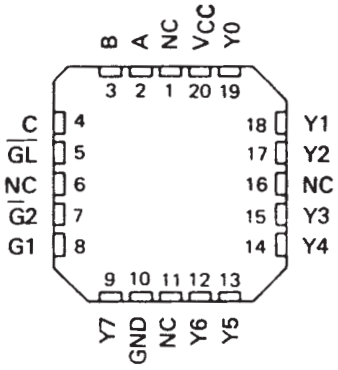
- **Combines Decoder and 3-Bit Address Latch**
- **Incorporates 2 Enable Inputs to Simplify Cascading**
- **Low Power Dissipation . . . 65 mW Typ**

SN54LS137 . . . J OR W PACKAGE
SN74LS137 . . . D OR N PACKAGE
(TOP VIEW)



SN54LS137 . . .FK PACKAGE
(TOP VIEW)

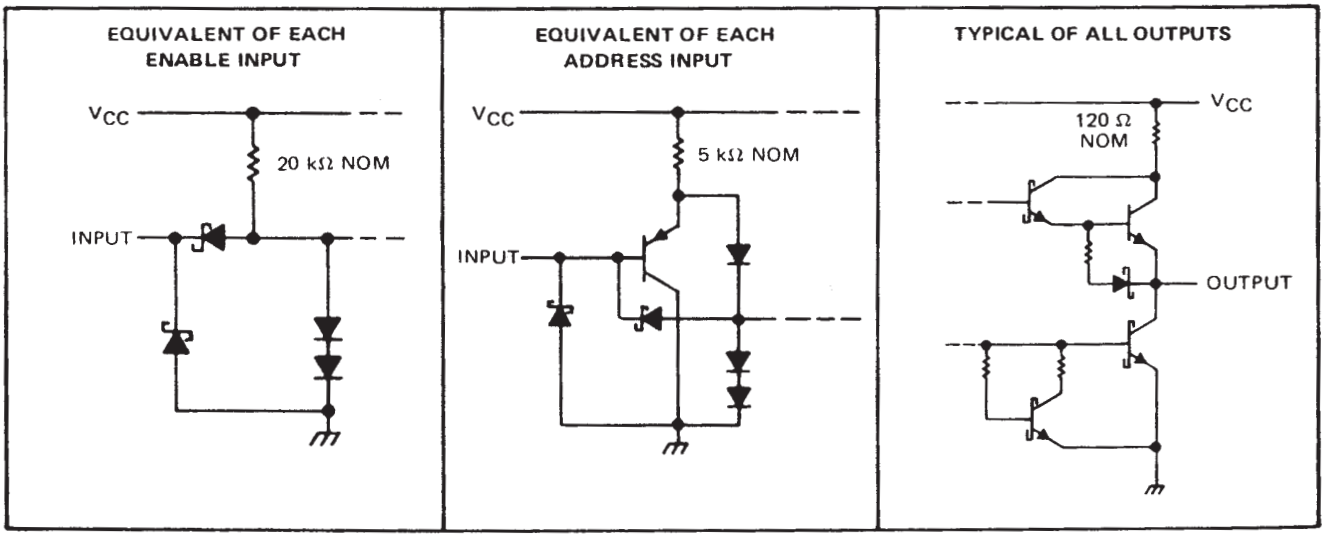


NC - No internal connection

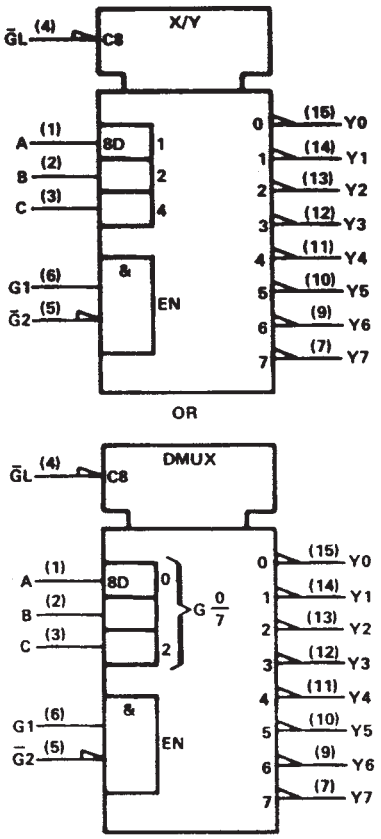
description

The 'LS137 is a three-line to eight-line decoder/demultiplexer with latches on the three address inputs. When the latch-enable input ($\overline{GL}$) is low, the 'LS137 acts as a decoder/demultiplexer. When $\overline{GL}$ goes from low to high, the address present at the select inputs (A,B, and C) is stored in the latches. Further address changes are ignored as long as $\overline{GL}$ remains high. The output enable controls, G1 and $\overline{G2}$, control the state of the outputs independently of the select or latch-enable inputs. All of the outputs are high unless G1 is high and $\overline{G2}$ is low. The 'LS137 is ideally suited for implementing glitch-free decoders in strobed (stored-address) applications in bus-oriented systems.

schematics of inputs and outputs



logic symbols†



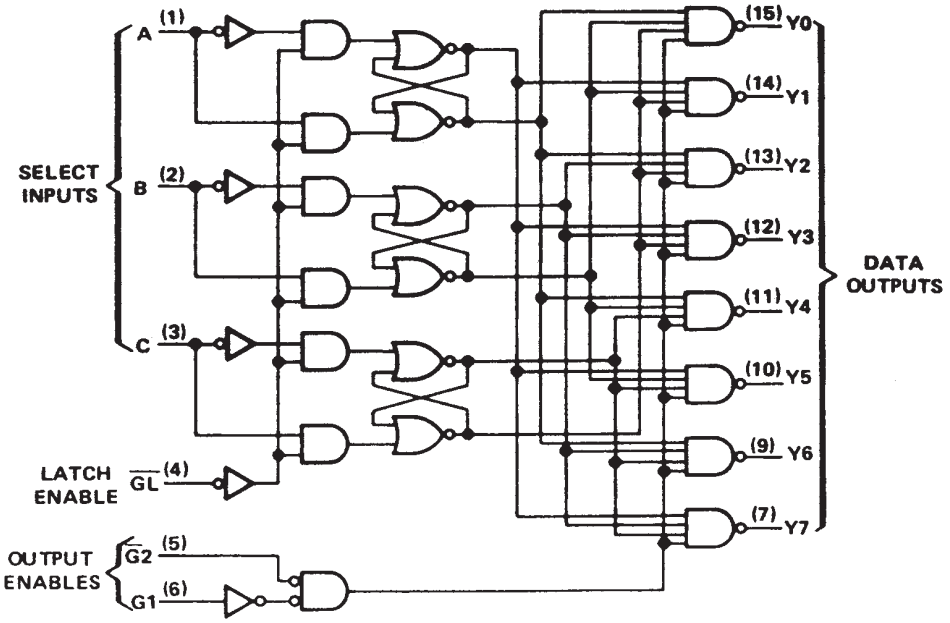
†These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for D, J, N, and W packages.

FUNCTION TABLE

INPUTS						OUTPUTS							
ENABLE			SELECT										
$\overline{G1}$	G1	$\overline{G2}$	C	B	A	Y0	Y1	Y2	Y3	Y4	Y5	Y6	Y7
X	X	H	X	X	X	H	H	H	H	H	H	H	H
X	L	X	X	X	X	H	H	H	H	H	H	H	H
L	H	L	L	L	L	L	H	H	H	H	H	H	H
L	H	L	L	L	H	H	L	H	H	H	H	H	H
L	H	L	L	H	L	H	H	L	H	H	H	H	H
L	H	L	L	H	H	H	H	H	L	H	H	H	H
L	H	L	H	L	L	H	H	H	H	L	H	H	H
L	H	L	H	L	H	H	H	H	H	H	L	H	H
L	H	L	H	H	L	H	H	H	H	H	H	L	H
L	H	L	H	H	H	H	H	H	H	H	H	H	L
H	H	L	X	X	X	Output corresponding to stored address, L; all others, H							

H = high level, L = low level, X = irrelevant

logic diagram (positive logic)



Pin numbers shown are for D, J, N, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (See Note 1) . . . . . 7 V
Input voltage . . . . . 7 V
Operating free-air temperature range: SN54LS137 . . . . . −55°C to 125°C
SN74LS137 . . . . . 0°C to 70°C
Storage temperature range . . . . . −65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

	SN54LS137			SN74LS137			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}	4.5	5	5.5	4.75	5	5.25	V
High-level output current, I_{OH}			–400			–400	μA
Low-level output current, I_{OL}			4			8	mA
Width of enabling pulse at $\overline{G}L$, t_w	15			15			ns
Setup time at A, B, and C inputs, t_{su}	10			10			ns
Hold time at A, B, and C inputs, t_h	10			10			ns
Operating free-air temperature, T_A	–55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†			SN54LS137			SN74LS137			UNIT
					MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IH}	High-level input voltage				2			2			V
V_{IL}	Low-level input voltage						0.7			0.8	V
V_{IK}	Input clamp voltage	V_{CC} = MIN,	I_I = –18 mA				–1.5			–1.5	V
V_{OH}	High-level output voltage	V_{CC} = MIN, V_{IL} = V_{IL} max,	V_{IH} = 2 V, I_{OH} = –400 μA		2.5	3.5		2.7	3.5		V
V_{OL}	Low-level output voltage	V_{CC} = MIN, V_{IL} = V_{IL} max	V_{IH} = 2 V,	I_{OL} = 4 mA		0.25	0.4		0.25	0.4	V
				I_{OL} = 8 mA					0.35	0.5	
I_I	Input current at maximum input voltage	V_{CC} = MAX,	V_I = 7 V				0.1			0.1	mA
I_{IH}	High-level input current	V_{CC} = MAX,	V_I = 2.7 V				20			20	μA
I_{IL}	Low-level input current	V_{CC} = MAX,	V_I = 0.4 V	Enable			–0.4			–0.4	mA
				A, B, C			–0.2			–0.2	
I_{OS}	Short-circuit output current§	V_{CC} = MAX			–20		–100	–20		–100	mA
I_{CC}	Supply current	V_{CC} = MAX,	See Note 2			11	18		11	18	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.
§ Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.
NOTE 2: I_{CC} is tested with all inputs grounded and all outputs open.

switching characteristics, V_{CC} = 5 V, T_A = 25°C, see note 3

PARAMETER¶	FROM (INPUT)	TO (OUTPUT)	LEVELS OF DELAY	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	A, B, C	Y	2	C_L = 15 pF, R_L = 2 kΩ, See Note 3		11	17	ns
t_{PHL}			4			25	38	
t_{PLH}	A, B, C	Y	3			16	24	ns
t_{PHL}			3			19	29	
t_{PLH}	Enable $\overline{G}2$	Y	2			13	21	ns
t_{PHL}			2			16	27	
t_{PLH}	Enable G1	Y	3			14	21	ns
t_{PHL}			3			18	27	
t_{PLH}	Enable $\overline{G}L$	Y	3			18	27	ns
t_{PHL}			4			25	38	

¶ t_{PLH} = propagation delay time, low-to-high-level output.
t_{PHL} = propagation delay time, high-to-low-level output.
NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN54LS137J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS137J	Samples
SNJ54LS137J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS137J	Samples
SNJ54LS137J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS137J	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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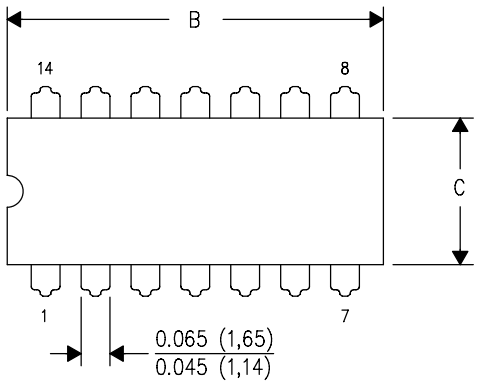
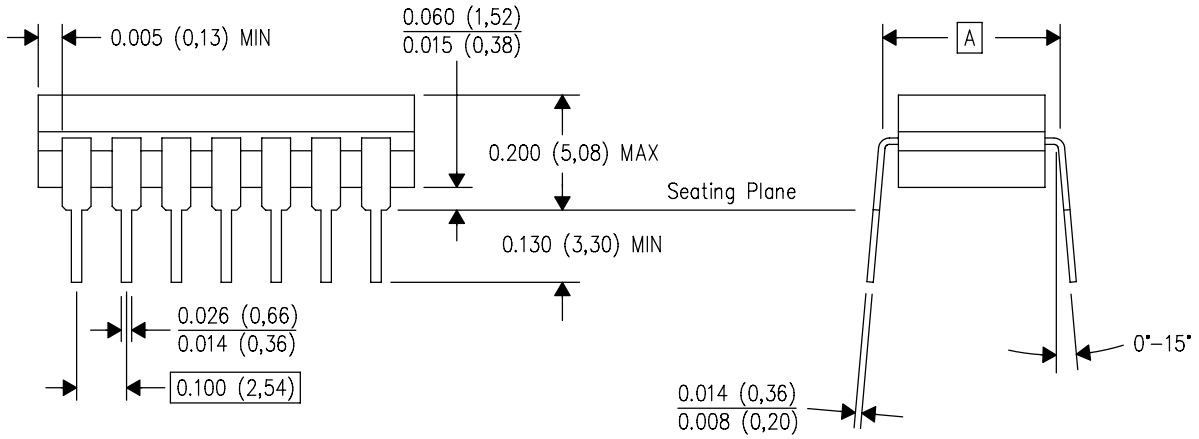
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

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